

BUK9Y1R3-40HX-VB Datasheet

N-Channel 40-V (D-S) MOSFET

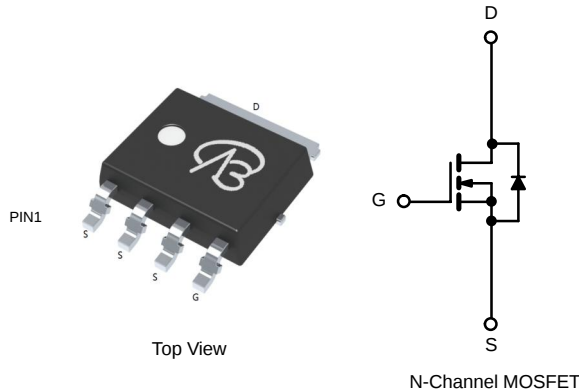
PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^{a, c}	Q_g (Typ.)
40	0.0007 at $V_{GS} = 10$ V	150	80 nC
	0.0008 at $V_{GS} = 7.5$ V	120	

FEATURES

- SGT Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies



ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 25	
Continuous Drain Current ($T_J = 175$ °C)	$T_C = 25$ °C	I_D	150 ^{a, c}	A
	$T_C = 70$ °C		96 ^c	
	$T_A = 25$ °C		29 ^b	
	$T_A = 70$ °C		23 ^b	
Pulsed Drain Current		I_{DM}	450	
Avalanche Current Pulse		I_{AS}	80	
Single Pulse Avalanche Energy		E_{AS}	320	mJ
Continuous Source-Drain Diode Current	$T_C = 25$ °C	I_S	120 ^{a, c}	A
	$T_A = 25$ °C		2.6 ^b	
Maximum Power Dissipation	$T_C = 25$ °C	P_D	375 ^a	W
	$T_C = 70$ °C		263	
	$T_A = 25$ °C		3.75 ^b	
	$T_A = 70$ °C		2.6 ^b	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	Steady State	R_{thJA}	32	40	°C/W
	Steady State	R_{thJC}	0.33	0.4	

Notes:

a. Based on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 150 A.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	40			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		41		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 8		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2		4	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μA
		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C			10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	150			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A		0.0007		Ω
		V _{GS} = 7.5 V, I _D = 20 A		0.0008		
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 30 A		100		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz		6000		pF
Output Capacitance	C _{oss}			1650		
Reverse Transfer Capacitance	C _{rss}			450		
Total Gate Charge	Q _g	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 20 A		80	100	nC
Gate-Source Charge	Q _{gs}			30		
Gate-Drain Charge	Q _{gd}			16		
Gate Resistance	R _g	f = 1 MHz		0.85	1.3	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 20 V, R _L = 1.0 Ω I _D ≅ 20 A, V _{GEN} = 10 V, R _g = 1 Ω		20	30	ns
Rise Time	t _r			11	17	
Turn-Off Delay Time	t _{d(off)}			77	115	
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 20 V, R _L = 1.0 Ω I _D ≅ 20 A, V _{GEN} = 4.5 V, R _g = 1 Ω		20		
Rise Time	t _r			18		
Turn-Off Delay Time	t _{d(off)}			50		
Fall Time	t _f			30		
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			120	A
Pulse Diode Forward Current ^a	I _{SM}				200	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		50		ns
Body Diode Reverse Recovery Charge	Q _{rr}			40	65	nC
Reverse Recovery Fall Time	t _a			20		ns
Reverse Recovery Rise Time	t _b			17		

Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

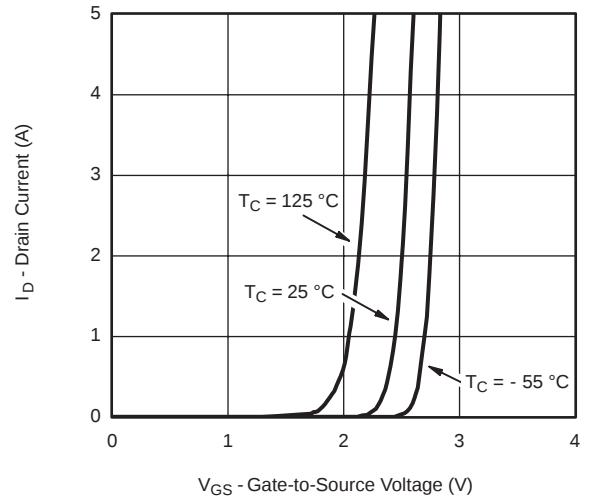
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Output Characteristics



Transfer Characteristics



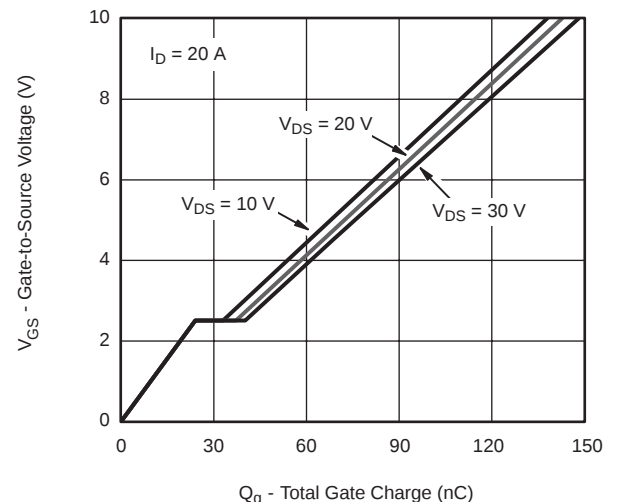
Transconductance



On-Resistance vs. Drain Current



Capacitance

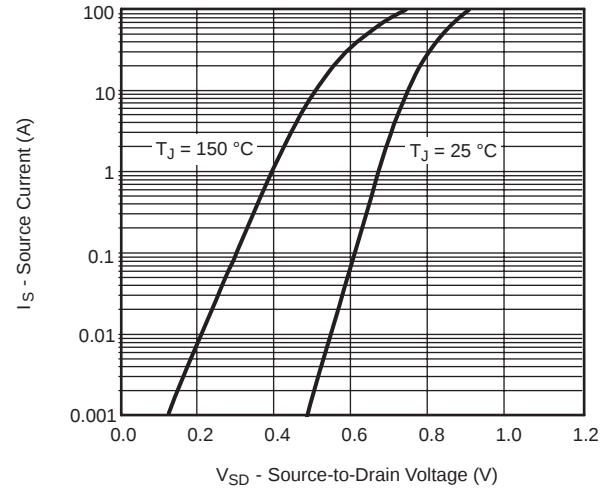


Gate Charge

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Junction Temperature



Forward Diode Voltage vs. Temperature



On-Resistance vs. Gate-to-Source Voltage



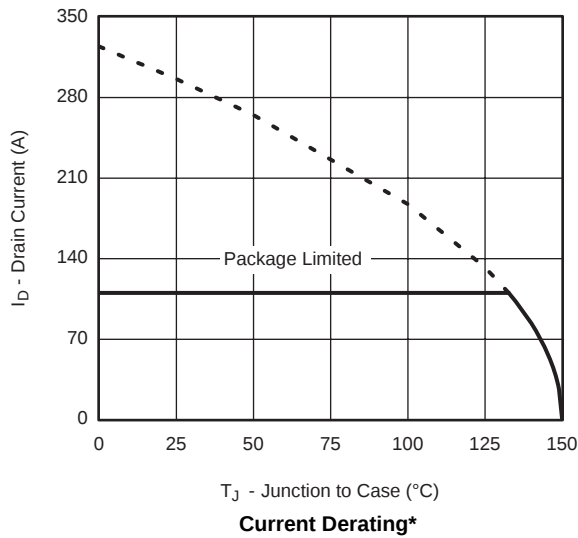
Threshold Voltage



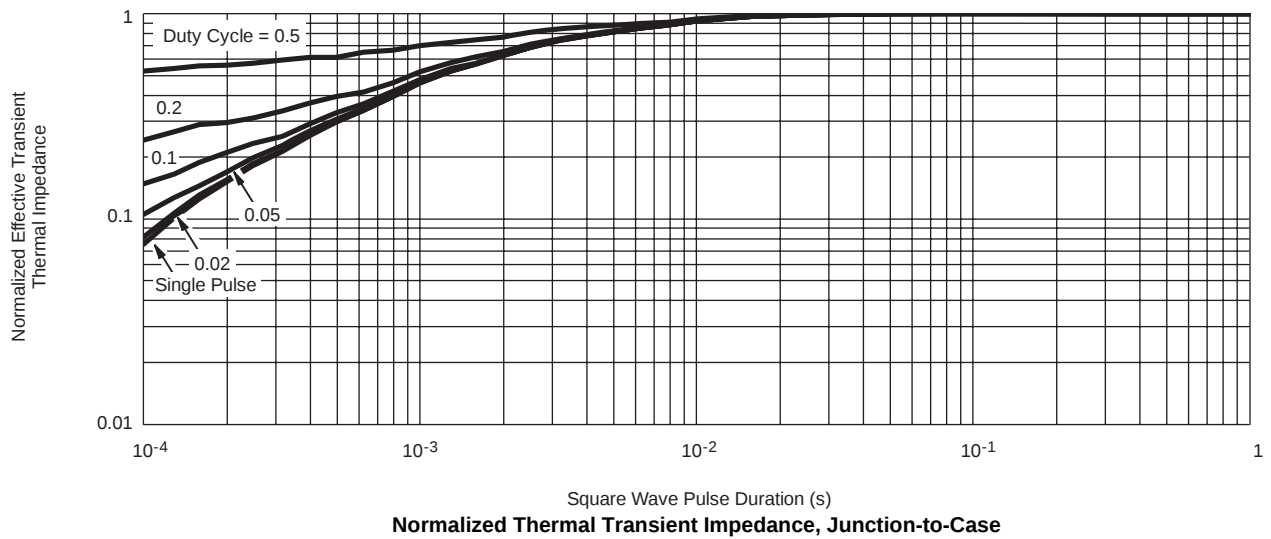
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

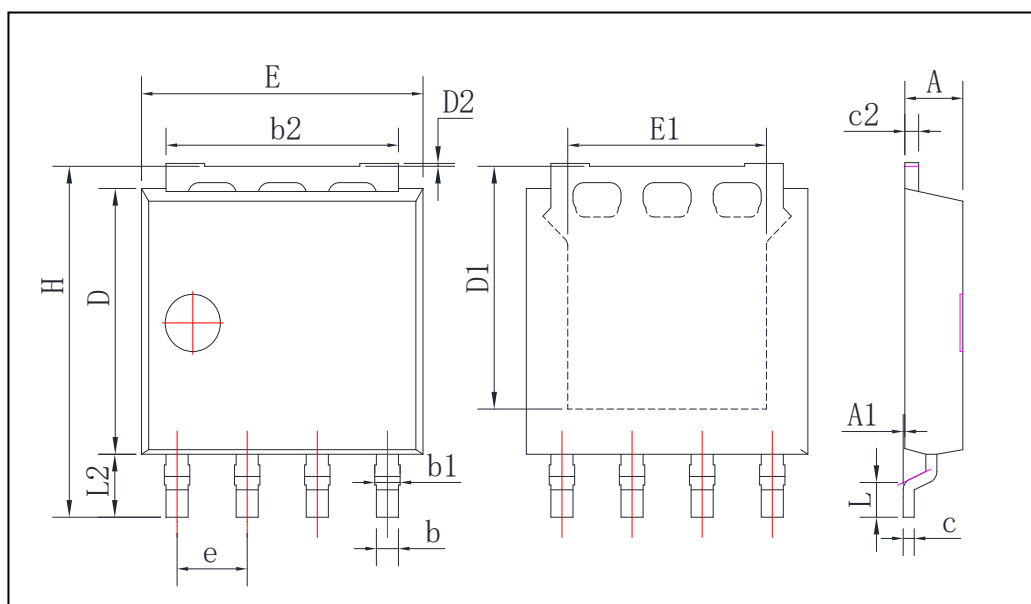
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



LFPAK56 CASE OUTLINE



Symbol	Min	Typ	Max
A	1.00	1.05	1.10
A1	0.00		0.15
b	0.35	0.40	0.50
b1	0.40	0.48	0.58
b2	4.01	4.21	4.41
c	0.18	0.20	0.25
c2	0.23	0.25	0.30
D	4.44	4.59	4.70
D1	4.10	4.24	4.40
D2			0.20
e	1.22	1.27	1.32
E	5.00	5.10	5.25
E1	3.50	3.60	3.70
H	6.05	6.15	6.25
L	0.40	0.60	0.80
L2	0.90	1.10	1.30

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